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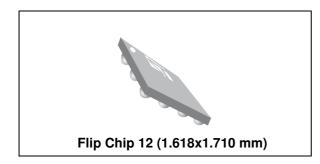






100 mA triple DC-DC converter for powering AMOLED displays

Data brief



Features

- Operating input voltage range from 2.9 V to 4.5 V
- 100 mA output current for step-up converters (V_{IN} > 2.9 V)
- 55 mA output current for auxiliary step-up converters (V_{IN} > 2.9 V)
- Step-up converter fixed at 4.6 V positive voltage
- Programmable negative voltage from 0.8 V to - 4.6 V default -3.0 V
- Auxiliary step-up converter positive voltage programmable step from 6.6 V to 7.6 V default 7.0 V
- Soft-start with inrush current protection
- Overtemperature protection
- True-shutdown mode
- Short-circuit protection
- Package Flip Chip 12 bumps (1.618x1.710 mm), 0.4 mm pitch

Applications

- Active matrix OLED power supply in portable devices
- Cellular phones, multimedia players, camcorders and digital cameras

Description

The STOD32W is a triple DC-DC converter for AMOLED display panels. It integrates a step-up of 100 mA, inverting DC-DC converters and an auxiliary step-up converter. This device is particularly suitable for battery operated products, in which the major concern is the overall system efficiency. All three output voltages can be programmed by a dedicated pin, which implements S_{WIRE} protocol. The auxiliary step-up positive output voltage is also configured by an external pull-down resistor. Soft-start with controlled inrush current limit, thermal shutdown and short-circuit protection are integrated functions of the device.

Table 1. Device summary

Order code	Negative voltage	Auxiliary positive voltage	Package	Packaging
STOD32WJR	-0.8 to -4.6 V	6.6 to 7.6 V	Flip Chip 12 (1.618x1.710 mm)	5000 parts per reel

1 Application schematic

1 L3 10 μH 1_L2 4.7 μH 2 GND L1 4.7 μH 2 1 VIN, CINP LX2 VO3 GND VO3 LX1 LX3 CINA СОЗ <u>V</u>O1 VO' Swire S_WIRE CO1 STOD32W GND VO2 VO2 ENO3 EN_VO3 CO2 PGND AGND GND ĠŃD GND GIPG2805141200LM

Figure 1. Application schematic

Table 2. Typical external components

Reference	Manufacturer	Part Number	Value	Size	Ratings
L1, L2, L3	токо	1239AS-H-100N=P2		2520 1.2T	1.0 A 0.460 Ω
	CYNTEC	PITB20161T-100MDR	10 μH 20161T-100MDR		0.8 A 0.750 Ω
CINP, CINA, CO1, CO2, CO3	SEMCO	CL10A226MP8NUN CL05A106MP5NUN	22 μF 10 μF	1608 1005	X5R 10 V ±20%

Note: All the above components refer to the typical application performance characteristics. Operation of the device is not limited to the choice of these external components.

2 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.



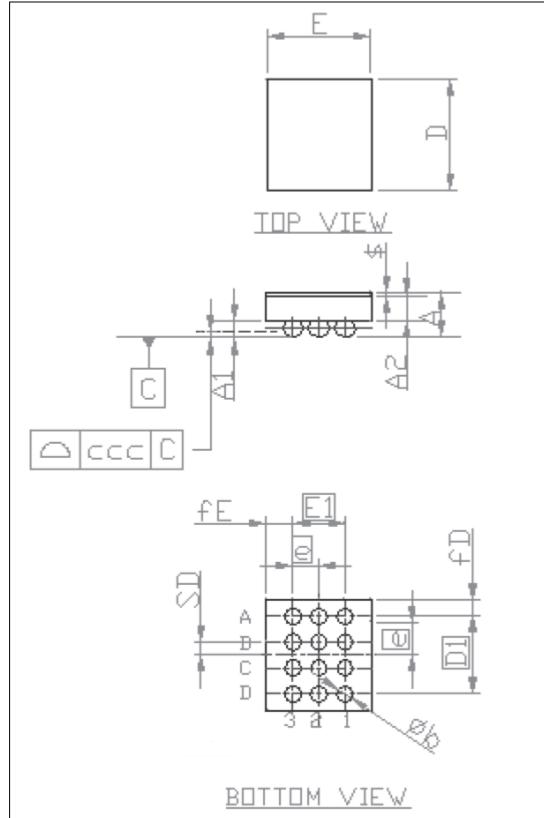
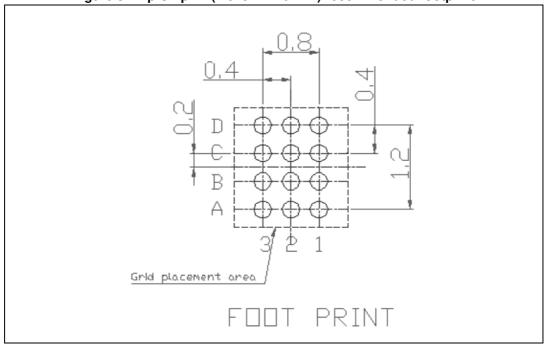


Figure 2. Flip Chip 12 (1.618x1.710 mm) drawings

Table 3. Flip Chip 12 (1.618x1.710 mm) mechanical data

Dim.	mm			
	Min.	Тур.	Max.	
Α	0.49	0.55	0.61	
A1	0.17	0.20	0.23	
A2	0.27	0.30	0.33	
b	0.23	0.26	0.29	
D	1.68	1.71	1.74	
D1		1.20		
E	1.588	1.618	1.648	
E1		0.80		
е		0.40		
fD		0.255		
fE		0.409		
SD		0.20		
ccc		0.08		
\$		0.05		

Figure 3. Flip Chip 12 (1.618x1.710 mm) recommended footprint



Note: All dimensions are in mm.

Revision history STOD32W

3 Revision history

Table 4. Document revision history

Date	Revision	Changes
04-Jun-2014	1	Initial release.

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